

FAST TURN-OFF THYRISTORS



Glass-passivated, asymmetrical, fast turn-off, forward blocking thyristors (ASCR) in TO-48 envelopes, suitable for operation in fast power inverters. For reverse-blocking operation use with a series diode, for reverse-conducting operation use with an anti-parallel diode.

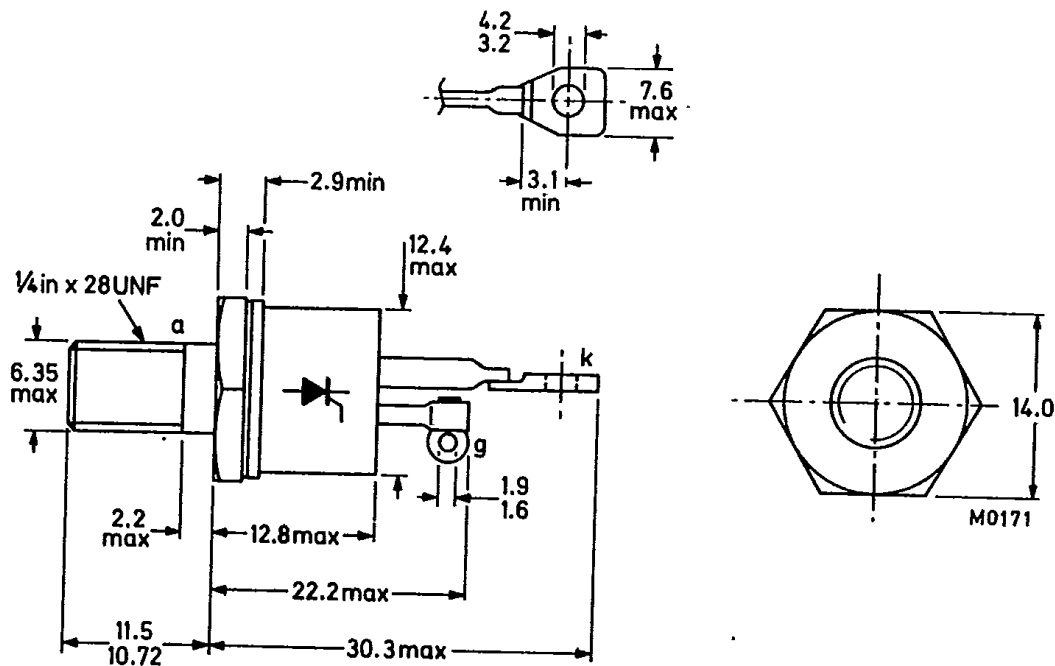
QUICK REFERENCE DATA

		BTW63-600R	800R	1000R	
Repetitive peak off-state voltage	V_{DRM}	max. 600	800	1000	V
Average on-state current	$I_{T(AV)}$	max.	25		A
Repetitive peak on-state current	I_{TRM}	max.	250		A
Circuit-commutated turn-off time					
suffix K	t_q	<	4		μs
suffix N	t_q	<	6		μs

MECHANICAL DATA

Fig.1 TO-48

Dimensions in mm



Net Mass. 14 g

Diameter of clearance hole. max. 6.5 mm

Accessories supplied on request:

56264a (mica washer);

56264b (insulating bush).

Supplied with device: 1 nut, 1 lock washer.

Torque on nut: min. 1.7 Nm (17 kg cm)

max. 3.5 Nm (35 kg cm)

Nut dimensions across the flats: 11.1 mm

Products approved to CECC 50 011-010 available on request.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Anode to cathode		BTW63-600R	800R	1000R	
Transient off-state voltage	V_{DSM}	max. 800	1000	1000	V
Repetitive peak off-state voltage	V_{DRM}	max. 600	800	1000	V
Continuous off-state voltage	V_D	max. 500	650	700	V
Transient reverse voltage ($t_p \leq 5 \mu s$)		V_{RSM}	max.	15	V
Average on-state current averaged over any 20 ms period; → up to $T_{mb} = 85^\circ C$		$I_T(AV)$	max.	25	A
R.M.S. on-state current		$I_T(RMS)$	max.	40	A
Repetitive peak on-state current; $t_p = 50 \mu s$; $\delta = 0.05$		I_{TRM}	max.	250	A
Non-repetitive peak on-state current $T_j = 125^\circ C$ prior to surge; $t = 10$ ms; half sine-wave		I_{TSM}	max.	370	A
$I^2 t$ for fusing; $t = 10$ ms		$I^2 t$	max.	700	$A^2 s$
Rate of rise of on-state current after triggering with $I_G = 1.25$ A; $I_T = 80$ A		di_T/dt	max.	1000	$A/\mu s$
Gate to cathode					
Average power dissipation (averaged over any 20 ms period)		$P_G(AV)$	max.	1	W
Peak power dissipation; $t = 10 \mu s$		P_{GM}	max.	10	W
Temperatures					
Storage temperature		T_{stg}		-40 to +125	$^\circ C$
Operating junction temperature		T_j	max.	125	$^\circ C$
THERMAL RESISTANCE					
→ From junction to mounting base		$R_{th j-mb}$	=	0.8	K/W
From mounting base to heatsink with heatsink compound		$R_{th mb-h}$	=	0.2	K/W

OPERATING NOTE

The terminals should be neither bent nor twisted; they should be soldered into the circuit so that there is no strain on them.
During soldering the heat conduction to the junction should be kept to a minimum.

CHARACTERISTICS

Anode to cathode

On-state voltage

$I_T = 50 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$

V_T	<	2.6	V*
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Off-state current

$V_D = V_{Dmax}; T_j = 125 \text{ }^\circ\text{C}$

I_D	<	6.0	mA
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Holding current; $T_j = 25 \text{ }^\circ\text{C}$

I_H	<	400	mA
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Gate to cathode

Voltage that will trigger all devices

$V_D = 12 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$

V_{GT}	>	2.0	V
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Current that will trigger all devices

$V_D = 12 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$

I_{GT}	>	250	mA
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Switching characteristics (see Fig.2)

Circuit commutated turn-off time

$dV_D/dt = 500 \text{ V}/\mu\text{s}$ (linear to V_{DRMmax});

$R_{GK} = 10 \text{ } \Omega; V_G = 0; T_j = 125 \text{ }^\circ\text{C};$

when switched from $I_T = 100 \text{ A}; t_p = 150 \text{ } \mu\text{s}$

$-dI_T/dt = 50 \text{ A}/\mu\text{s}$

suffix K

suffix N

t_q	<	6	μs
t_q	<	9	μs

$-dI_T/dt = 10 \text{ A}/\mu\text{s}$

suffix K

suffix N

t_q	<	4	μs
t_q	<	6	μs

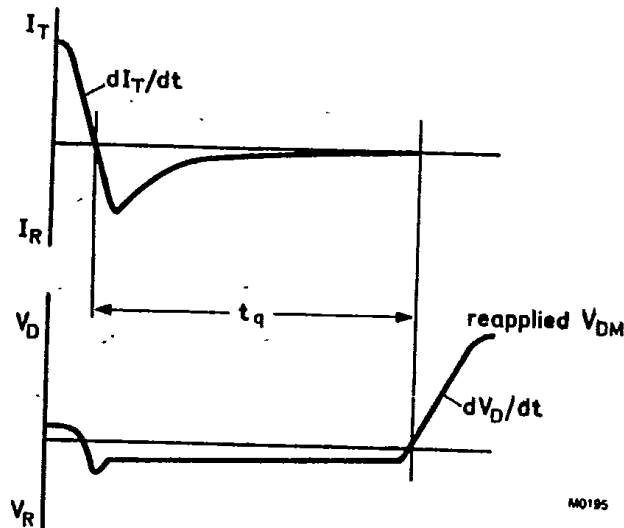


Fig.2 Circuit-commutated turn-off time definition.

*Measured under pulse conditions to avoid excessive dissipation.

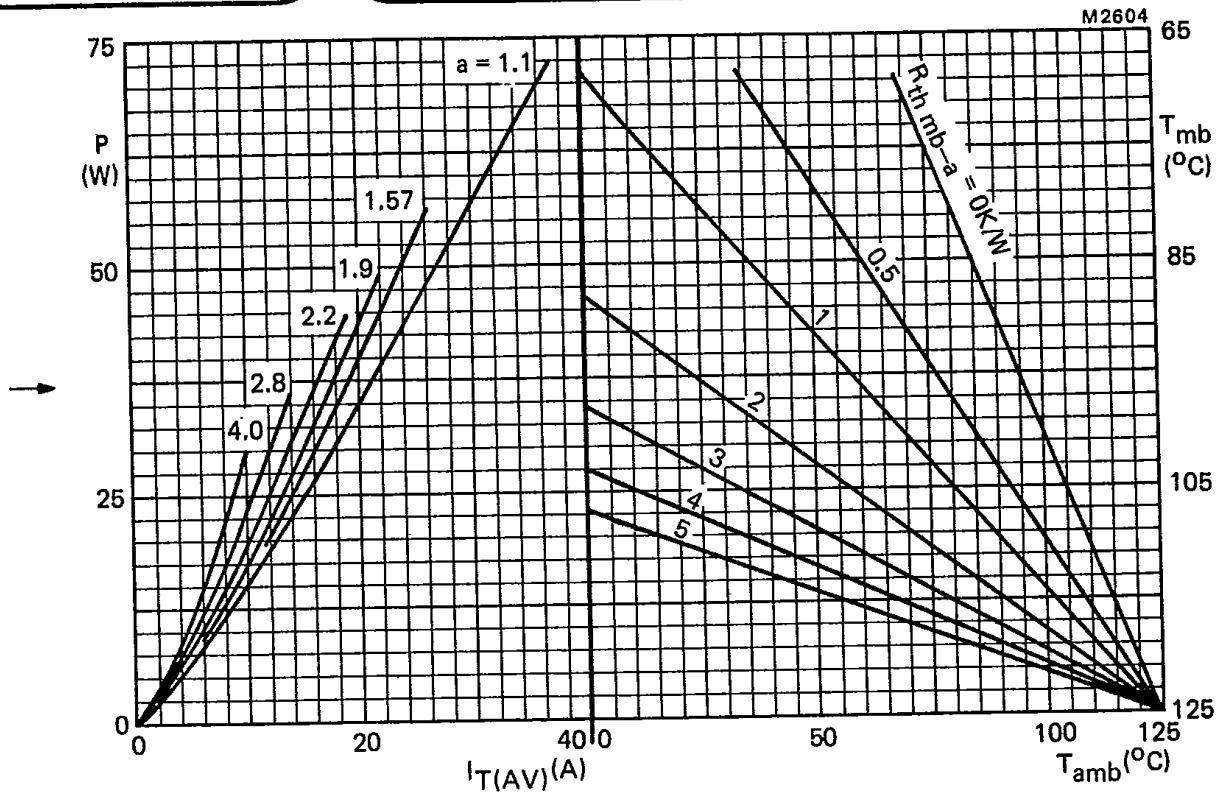


Fig.3 The right-hand part shows the interrelationship between the power (derived from the left-hand part) and the maximum permissible temperatures.

$$a = \text{form factor} = \frac{I_T(\text{RMS})}{I_T(\text{AV})}$$

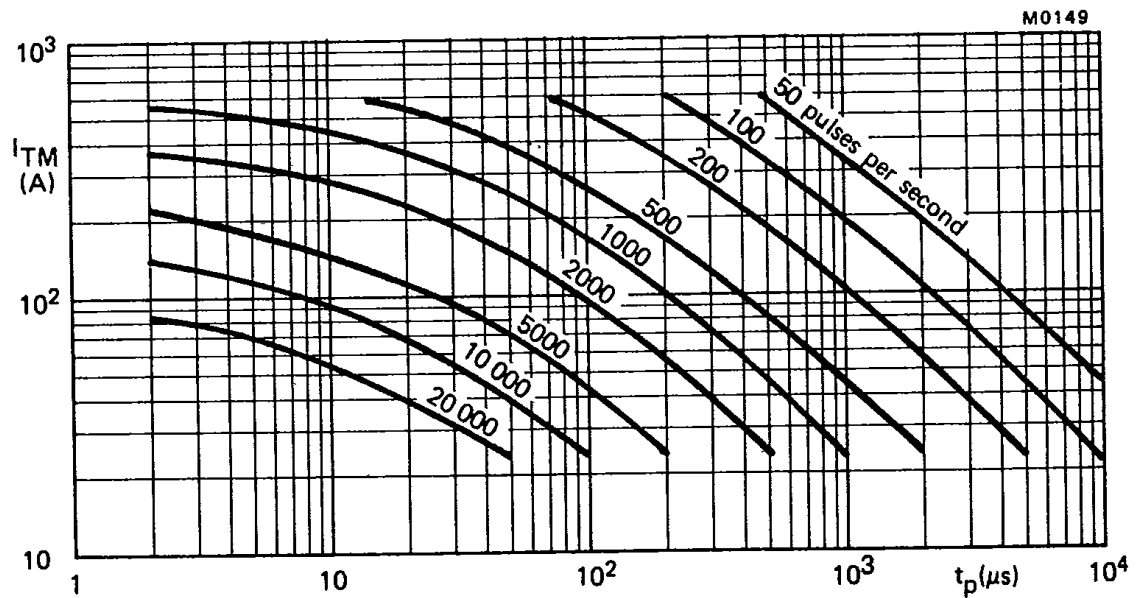


Fig.4 Maximum allowable peak on-state current versus pulse width; $T_{mb} = 85^\circ\text{C}$.

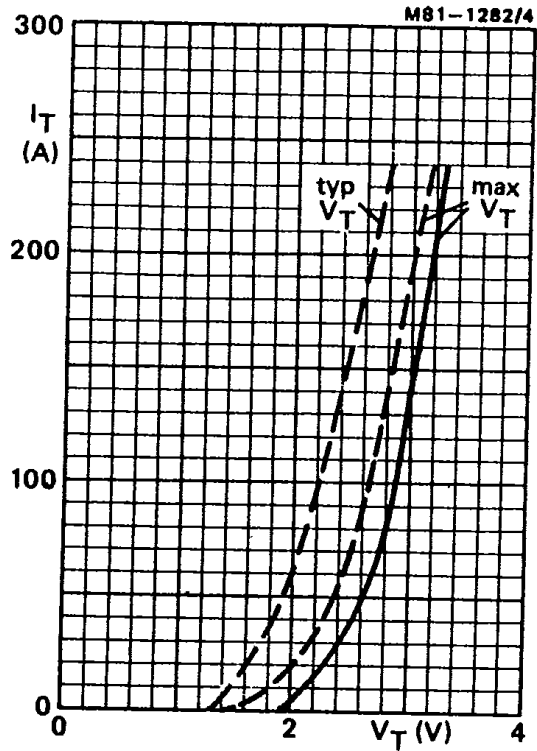


Fig.5 — $T_j = 25\text{ }^\circ\text{C}$; --- $T_j = 125\text{ }^\circ\text{C}$;
 $t_p = 200\text{ }\mu\text{s}$.

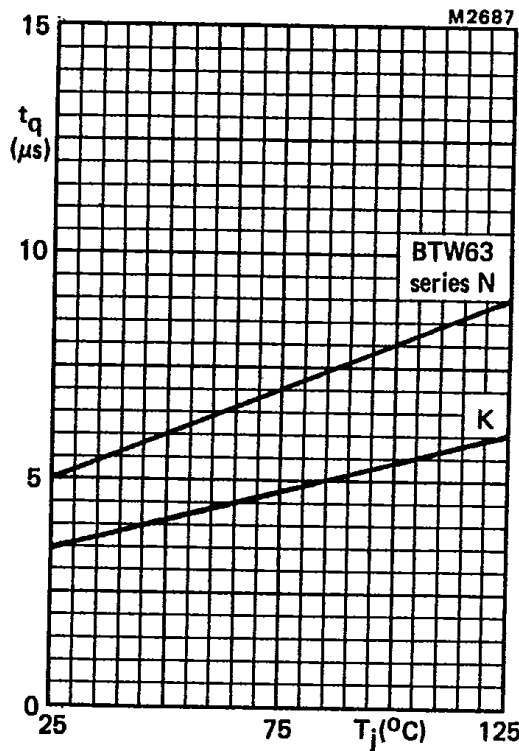


Fig.6a Variation of t_q with T_j ;
 $-di_T/dt = 50\text{ A}/\mu\text{s}$; $dV_D/dt = 500\text{ V}/\mu\text{s}$
 (linear to V_{DRMmax}); $I_T = 100\text{ A}$; $t_p = 150\text{ }\mu\text{s}$;
 $R_{GK} = 10\text{ }\Omega$; $V_G = 0$; maximum values.

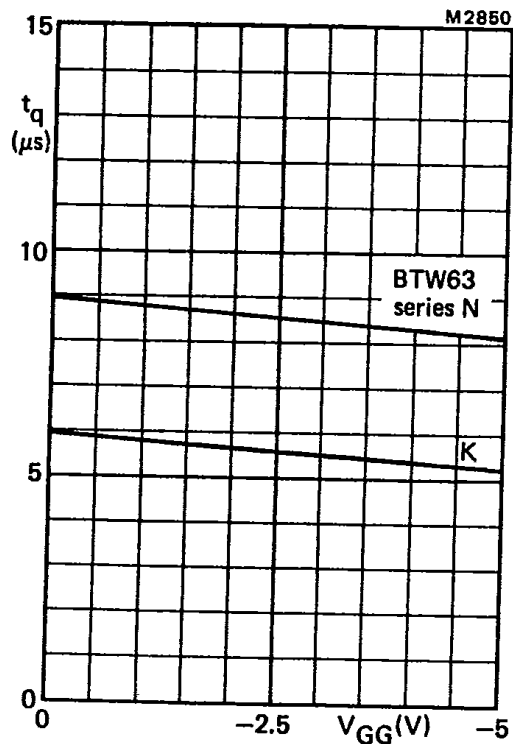


Fig.6b Variation of t_q with negative bias;
 $-di_T/dt = 50\text{ A}/\mu\text{s}$; $dV_D/dt = 500\text{ V}/\mu\text{s}$
 (linear to V_{DRMmax}); $I_T = 100\text{ A}$; $t_p = 150\text{ }\mu\text{s}$;
 $T_j = 125\text{ }^\circ\text{C}$; maximum values.

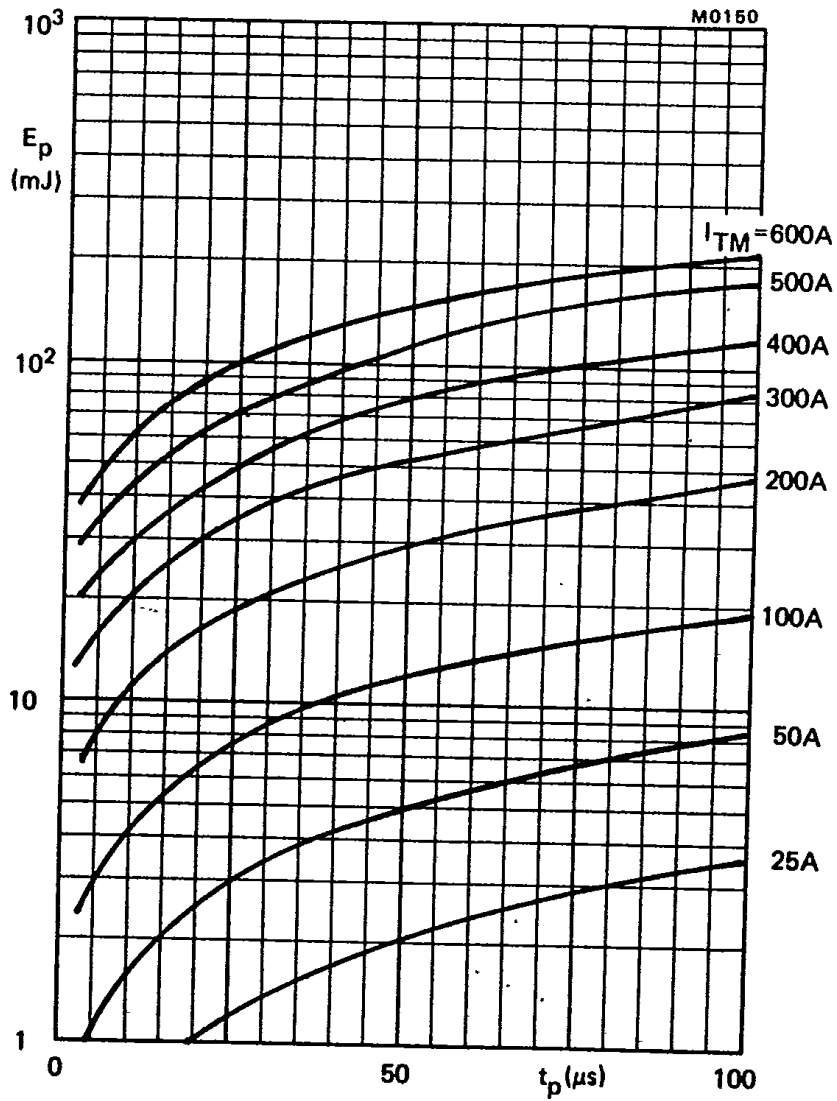


Fig.7 Maximum total energy loss per pulse when switching a half-sinusoidal pulse from 600 V.
 Device power (W) = Energy per pulse (J) x No. of pulses per second.
 For pulse widths > 100 μs use Fig.3.

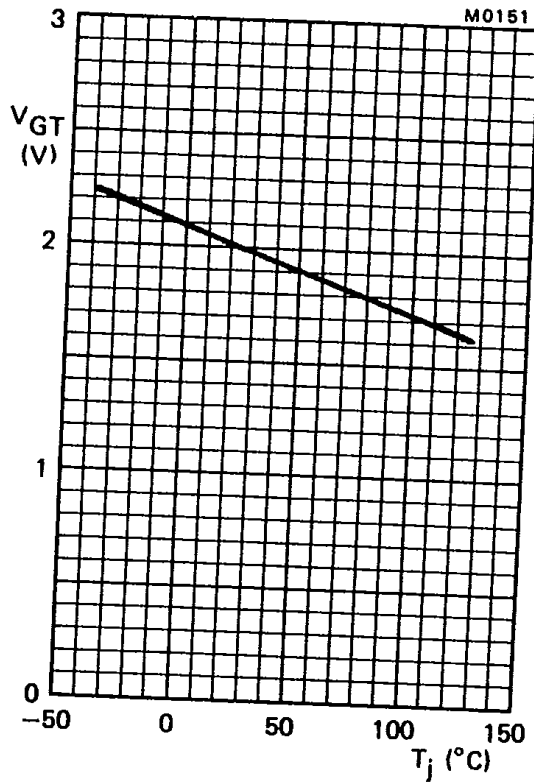


Fig.8 Minimum gate voltage that will trigger all devices plotted against junction temperature.

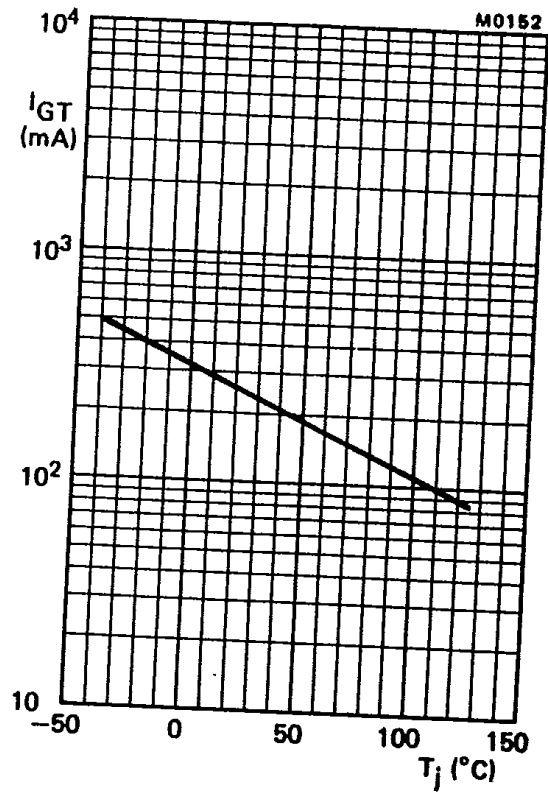


Fig.9 Minimum gate current that will trigger all devices plotted against junction temperature.